

CMP PROCESS: CONCEPTS & MEASUREMENTS

Who should attend?

This course is designed for those individuals in the semiconductor industry who require the knowledge of the concepts and measurement techniques for the Chemical Mechanical Polishing (CMP) process.

Course Benefits

Increase knowledge of:
Process fundamentals
Integration of process in wafer fabrication
Process measurement techniques
Post-PM process recovery

Course Objective Summary

- Describe the general concepts of the planarization techniques used in the semiconductor industry.
- Describe the concepts and principles related to the CMP process.
- Describe the hardware associated with the CMP process.
- Describe the parameters used for analyzing and improving the CMP process.
- Describe the importance of Post-CMP Cleaning in the CMP process.

Course Modules

1. *Safety*
2. *CMP Concepts*
3. *CMP Process Principles*
4. *CMP Hardware Overview*
5. *CMP Process Control & Monitoring*
6. *Post-CMP Cleaning*

Registration Information

Prerequisites: *None*

Course Length: *6 Hours*

Course Type: *Web-based Training*

Course Number: *TRNWEB-168*

To enroll or for more information on our products and services, please call our registrar at one of the numbers below or go to www.appliedtraining.com.

- 1-800-468-8888, option 4 (United States)
- 1-512-272-0027 (International)

Computer System Requirements:

Attending this course requires a Windows 98, NT, 2000 or XP computer using Internet Explorer 5.5 or higher. 128MB RAM or higher and high-speed Internet access is also highly recommended. For the audio portion of the class, headsets or speakers and a sound card are required.